### Specifications

<table>
<thead>
<tr>
<th>Application</th>
<th>Model</th>
<th>Exposure Area</th>
<th>Wavelength</th>
<th>Alignment</th>
<th>NA</th>
<th>Resolution</th>
</tr>
</thead>
<tbody>
<tr>
<td>Power Device</td>
<td>SPF-150 Series</td>
<td>150mm</td>
<td>365nm</td>
<td>Single Sided</td>
<td>0.14</td>
<td>2.0μm</td>
</tr>
<tr>
<td>CMOS Back Wiring</td>
<td>SPS-300 Series</td>
<td>300mm (150mm×4 step)</td>
<td>365nm</td>
<td>Double Sided</td>
<td>0.08</td>
<td>3.5μm</td>
</tr>
<tr>
<td>2.5D &amp; 3D Packaging</td>
<td>SPF-150 Series</td>
<td>150mm</td>
<td>365nm</td>
<td>Single Sided</td>
<td>0.14</td>
<td>2.0μm</td>
</tr>
<tr>
<td>LED (PSS)</td>
<td>SPF-100 Series</td>
<td>100mm</td>
<td>365nm</td>
<td>Double Sided</td>
<td>0.17</td>
<td>1.4μm</td>
</tr>
</tbody>
</table>

*We can also manufacture RTR projecting exposure system for FPC (flexible printed circuits).*

*Uses Seiwa Own designed and manufactured Projection lens.

### Features

- Projection aligner resolves problems below from contact and proximity exposure system.
- Adhesive Failure from Contact / Proximity exposure.
- Projection aligner is Non-Contact exposure system.
- Variability of Gap between mask and substrate.
- Projection aligner cancels variability of Gap by its larger focal depth.
- Smaller focal depth problem from Contact/ Proximity exposure.
- Projection aligner provides large focal depth of (14μm).
- Both side Alignment Accuracy: Topside ±1μm.
- Capacity: 90 wafers / hr.
- Backside: ±1μm.

### Mail Market

1) CMOS
2) Power device (Backside wiring)
   - Thick Resist, High Step Patterning
3) MEMS
4) LED (PSS)
5) Roll to Roll

### Options

1) Reticle Stocker
2) Automatic Reticle changer
3) Fully Automated / Semi Automated option
4) Magnification adjuster